Abstracts

Plastic microwave multi-chip modules for wireless communication applications

V. Krishnamurthy, E. Balch, K. Durocher, J. Rose, R. Saia, D. Lester and D. Sherwood. "Plastic microwave multi-chip modules for wireless communication applications." 1998 Radio Frequency Integrated Circuits (RFIC) Symposium 98. (1998 [RFIC]): 127-130.

This paper describes a high density, microwave plastic multi-chip module (MCM) with vertical feed throughs providing RF/DC I/Os at the module backside allowing for a low thermal resistance solder attach to a printed circuit board. A return loss of better than -20 dB up to approximately 3.8 GHz was measured for the coplanar vertical interconnect from the plastic module to a printed circuit board. Functional T/R modules operating between 1.60 GHz and 2.0 GHz were also fabricated with this technology.

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